



CIRCUIT TRACE KEEP OUT AREA
 SMT SOLDER AREA

THERE SHOULD NOT BE ANY CIRCUITRIES IN THE LAYOUT SPACE OF THE PRODUCTS.

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

NOTES:

MATERIAL:

Insulator: High Temperature Thermoplastic,
 Contact: Copper Alloy
 Shell: STAINLESS

PLATING:

Contact: Plated 30u" Ni Overall ,Solder Area: Tin,Contact G/F
 Shell: Plated 30u" Ni Overall
 Plated G/F Selective Contact Area

Electrical:

Current Rating :0.5mA max.
 Voltage Rating :50V DC MAX
 Ambient Temperature Range :-20°C~+85°C
 Storage Temperature Range :-40°C~+70°C
 Ambient Humidity Range :95% R.H. Max.
 Contact Resistance:100mΩ max.
 Insulation Resistance:1000M Ω min./250V DC
 Dielectric Withstanding Voltage:500V AC
 Mating Cycles:5,000 Insertions
 Temperature: 260°C ±5

SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

ITEM	PAPT NAMF	QTY	MATERIAL	FINISHING
③	Shell	1	SUS	
②	Terminal	6	COPPER ALLOY	
①	Housing	1	HI-TEMP.PLASIC UL 94V-0	BLACK

MARK	DESCRIPTION	REVISIONS	DATE	REVISED	APPROVED	UNSPECIFIED TOLERANCES	DSND	DATE	SCALE: N/A	MODEL TYPE: SIM CARD CONN
Δ X						ANGLAR ±5°	DWN	DATE	VIEW:	PART NO.:
Δ X						L ≤ 4 ±0.2	CHKD	DATE	UNIT: mm	DWG NO.: XKSIM-002-P6
Δ X						4 < L ≤ 16 ±0.3	APPD	DATE	SIZE: A4	
						16 < L ≤ 63 ±0.4				WEIGHT 1.0g
						L > 63 ±0.5				SHEET 1/1
										REVISION A0

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